

AMENDMENTS TO THE CLAIMS

1-2. (cancelled)

3. (Previously Presented) A method comprising:

forming a plurality of image sensor die having micro-lenses onto a semiconductor wafer,
wherein said image sensor die uses a ball grid array (BGA) on the underside of said
die;

forming a protective layer over said image sensor die;

dicing said wafer to separate said plurality of image sensor die;

mounting said image sensor die onto an integrated circuit package, the BGA being
positioned between the die and the integrated circuit package to electrically connect
the die to the integrated circuit package; and

removing said protective layer from said image sensor die.

4-5. (cancelled)